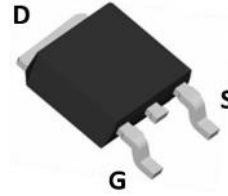


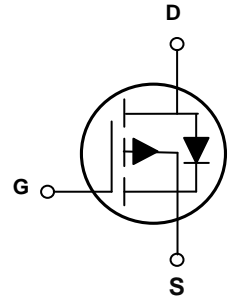
30V P-Channel MOSFET

Main Product Characteristics:

| | |
|---------------|-----------|
| $V_{(BR)DSS}$ | -30V |
| $R_{DS(ON)}$ | 7mΩ(max.) |
| I_D | -60A |



TO-252



Schematic Diagram

Features and Benefits

- Standard Turbo MOSFET process technology.
- Optimized the cell structure.
- Low on-resistance and low gate charge.
- Featuring low switching and drive losses.
- Fast switching and reverse body recovery.
- High ruggedness and robustness.



Description

The ST series products utilizes Trust's outstanding standard turbo process and packaging techniques to achieve ultral low on-resistance and low gate charge and to provide the industry's best-in-class performance.

These features make this series products extremely efficient, temperature characteristics and reliable for use in power management, synchronous rectification, battery protection, load switch and a wide variety of other applications.

Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

| Parameter | Symbol | Max. | Unit |
|---|-----------------|-------------|-----------------------------|
| Drain-Source Voltage | V_{DS} | -30 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current-Continuous ($T_C=25^{\circ}\text{C}$), $V_{GS}=10\text{V}^1$ | I_D | -60 | A |
| Drain Current-Continuous ($T_C=100^{\circ}\text{C}$), $V_{GS}=10\text{V}^1$ | | -45 | A |
| Drain Current-Pulsed ² | I_{DM} | -240 | A |
| Pulsed Source Current (Body Diode) ² | I_{SM} | -240 | A |
| Maximum Power Dissipation ($T_C=25^{\circ}\text{C}$) ³ | P_D | 70 | W |
| Single Pulse Avalanche Energy ($L=0.3\text{mH}$) | E_{AS} | 289 | mJ |
| Single Pulse Avalanche Current ($L=0.3\text{mH}$) | I_{AS} | 41 | A |
| Junction-to-Ambient ($t \leq 10\text{s}$) ⁴ | $R_{\theta JA}$ | 62 | $^{\circ}\text{C}/\text{W}$ |
| Maximum Junction-to-Case ⁵ | $R_{\theta JC}$ | 1.79 | $^{\circ}\text{C}/\text{W}$ |
| Operating Junction Temperature Range | T_J | -55 To +150 | $^{\circ}\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 To +150 | $^{\circ}\text{C}$ |



30V P-Channel MOSFET

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|--------------|---|------|-------|-----------|-----------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -30 | - | - | V |
| Drain-to-Source Leakage Current | I_{DSS} | $V_{DS}=-30V, V_{GS}=0V$ | - | - | -1 | μA |
| Drain-to-Source Leakage Current | | $V_{DS}=-30V, V_{GS}=0V, T_J=125^\circ\text{C}$ | - | - | -50 | μA |
| Gate-to-Source Leakage Current | I_{GSS} | $V_{GS}=\pm 20V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1.0 | -1.6 | -3 | V |
| Drain Static-Source On-Resistance | $R_{DS(on)}$ | $V_{GS}=-10V, I_D=-20A$ | - | 5.4 | 7 | $m\Omega$ |
| | | $V_{GS}=-4.5V, I_D=-15A$ | - | 8.7 | 9.7 | $m\Omega$ |
| Dynamic and Switching Characteristics | | | | | | |
| Total Gate Charge | Q_g | $V_{DD}=-15V, I_D=-20A, V_{GS}=-10V$ | - | 61 | - | nC |
| Gate-Source Charge | Q_{gs} | | - | 7.6 | - | |
| Gate-Drain Charge | Q_{gd} | | - | 15.2 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD}=-15V, R_G=3\Omega, R_L=0.75\Omega, V_{GS}=-10V, I_D=-20A$ | - | 21 | - | nS |
| Rise Time | t_r | | - | 18 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 26 | - | |
| Fall Time | t_f | | - | 8.2 | - | |
| Input Capacitance | C_{iss} | $V_{DS}=-15V, V_{GS}=0V, F=1\text{MHz}$ | - | 3230 | - | pF |
| Output Capacitance | C_{oss} | | - | 370 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 230 | - | |
| Gate Resitance | R_g | $F=1\text{MHz}$ | - | 3.5 | - | Ω |
| Source-Drain Ratings and Characteristics | | | | | | |
| Maximum Body-Diode Continuous Current | I_S | MOSFET symbol showing the integral reverse p-n junction diode. | - | -60 | - | A |
| Maximum Body-Diode Pulse Current | I_{SM} | | - | -240 | - | A |
| Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_S=-10A, T_J=25^\circ\text{C}$ | - | -0.85 | -1.2 | V |
| Reverse Recovery Time | t_{rr} | $I_F=-20A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$ | - | 15.1 | - | nS |
| Reverse Recovery Charge | Q_{rr} | | - | 20.5 | - | nC |

Notes:

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. The power dissipation P_D is based on max. junction temperature, using junction-to-case thermal resistance.
4. The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$

30V P-Channel MOSFET

Typical Electrical and Thermal Characteristic Curves

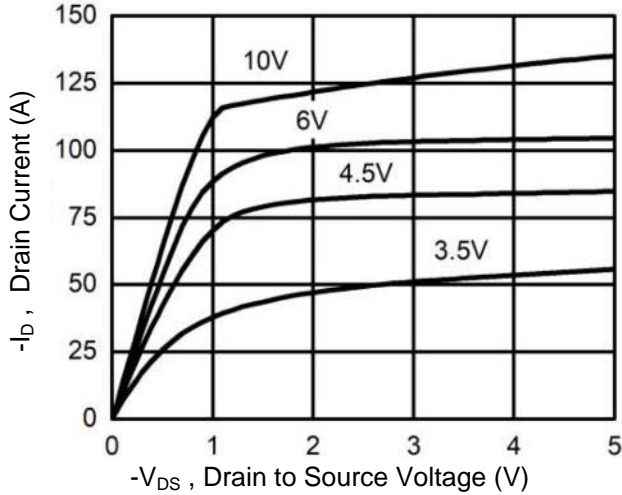


Fig.1 Typical Output Characteristics

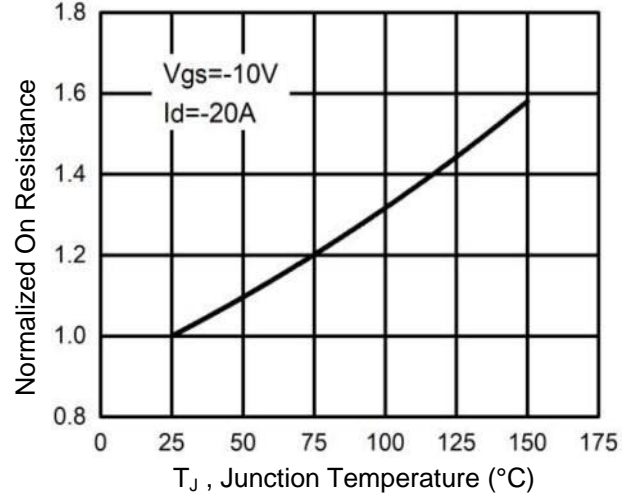


Fig.2 Normalized $R_{DS(ON)}$ vs. T_J

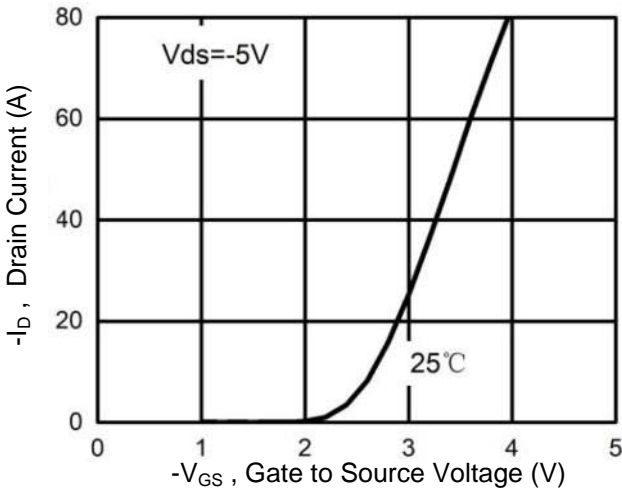


Fig.3 Typical Transfer Characteristics

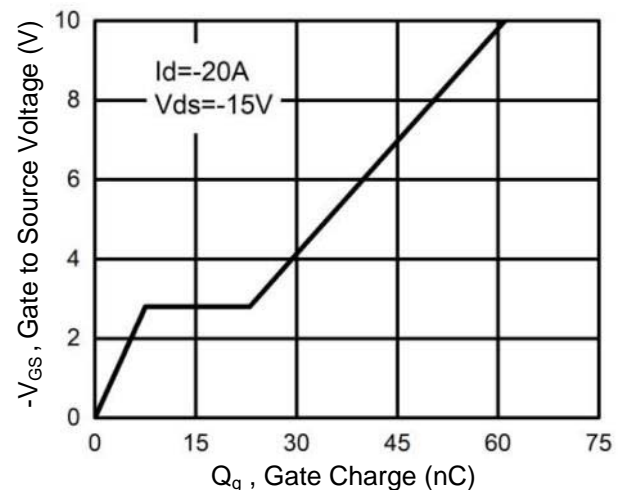


Fig.4 Gate Charge Waveform

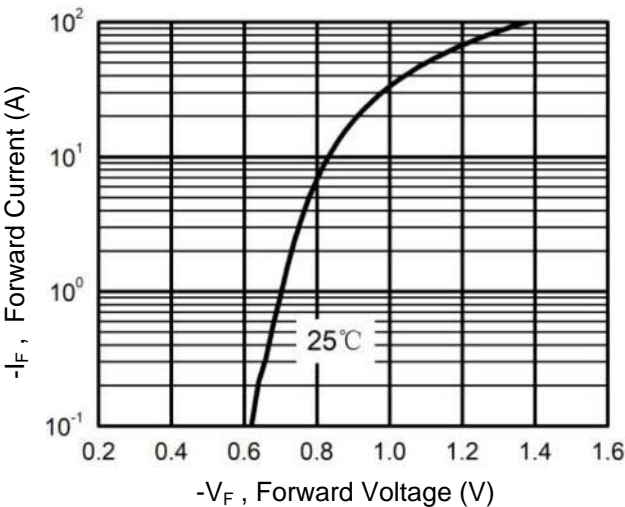


Fig.5 Typical Transfer Characteristics

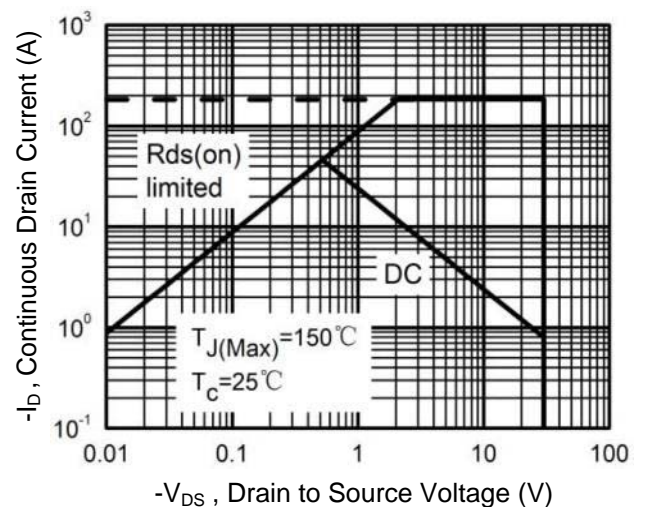


Fig.6 Maximum Safe Operation Area

30V P-Channel MOSFET

Test Circuits and Waveforms

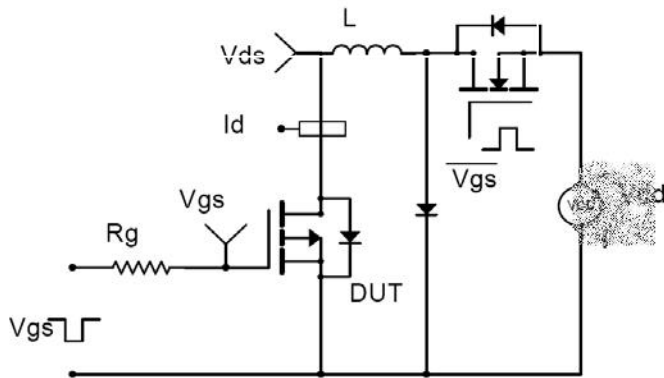


Figure 7. EAS Test Circuit

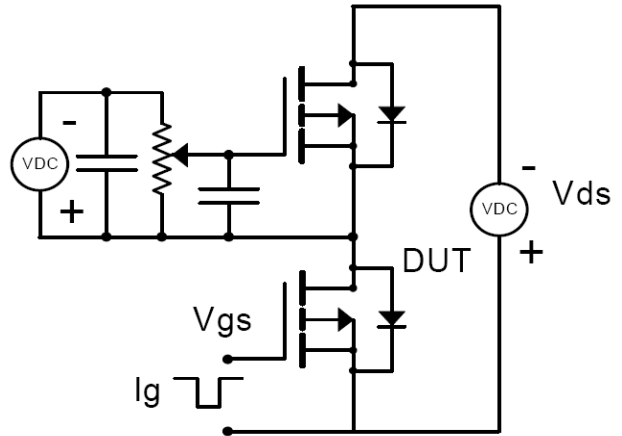


Figure 8. Gate Charge Test Circuit

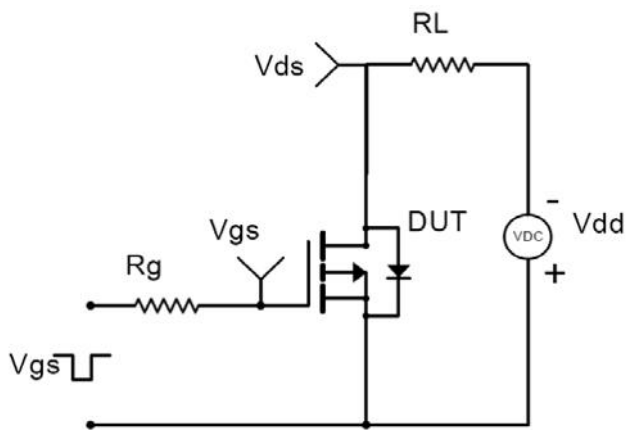


Figure 9. Switching Time Test Circuit

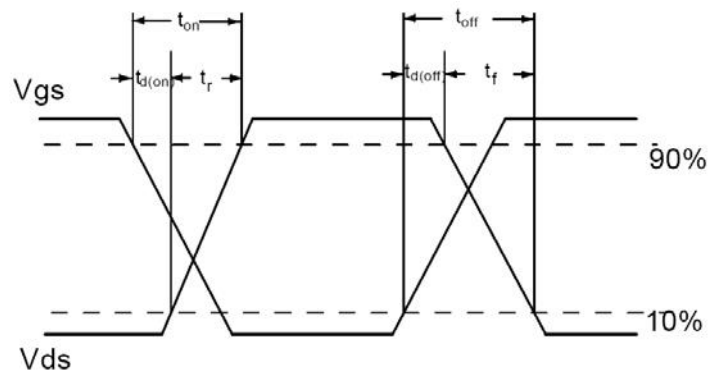
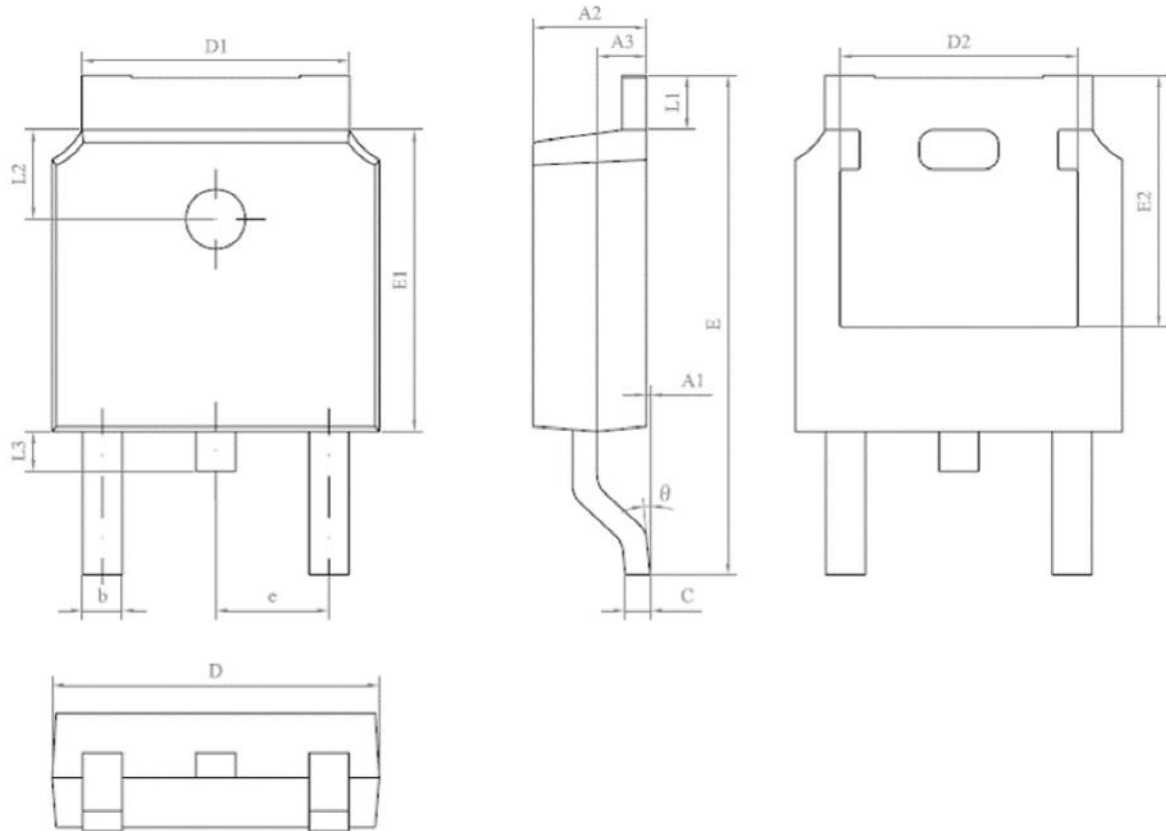


Figure 10. Switching Waveforms

30V P-Channel MOSFET

Package Outline Dimensions (TO-252/DPAK)



| Symbol | Dimensions In Millimeters | | Symbol | Dimensions In Millimeters | |
|--------|---------------------------|------|--------|---------------------------|------|
| | MAX | MIN | | MAX | MIN |
| A1 | 0.10 | 0.00 | E | 10.30 | 9.90 |
| A2 | 2.40 | 2.20 | E1 | 6.20 | 6.00 |
| A3 | 1.10 | 0.09 | E2 | 5.20 | 5.00 |
| b | 0.85 | 0.75 | e | 2.20 | 2.40 |
| C | 0.60 | 0.50 | L1 | 1.25 | 0.90 |
| D | 6.70 | 6.50 | L2 | 1.90 | 1.70 |
| D1 | 5.50 | 5.30 | L3 | 1.00 | 0.60 |
| D2 | 4.90 | 4.70 | θ | 8° | 0° |